

Micro Commercial Components Corp.

Tin Whisker Test Report for SMD-Cu

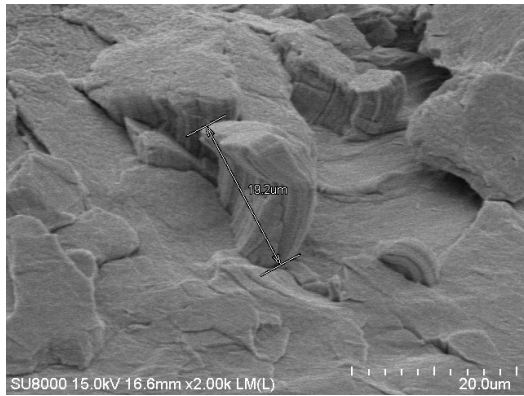
Test Purpose: Inspect the performance of whisker growth

Category: Copper base material with tin plating

Test Conditions:

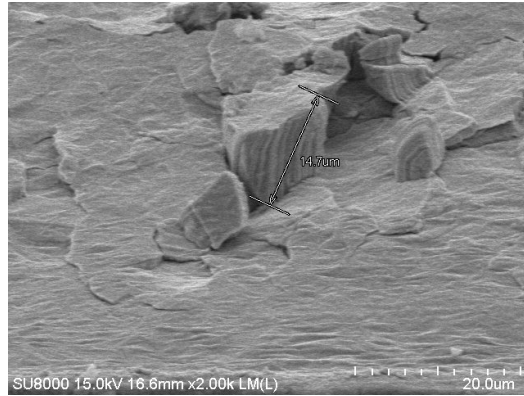
Test Items	Test Condition
TCT	-40°C~85°C,10min soak, 2000cycles
THT	30°C/60%RH, 4000Hrs
HT&H	55°C/85%RH,4000Hrs

Test Results:

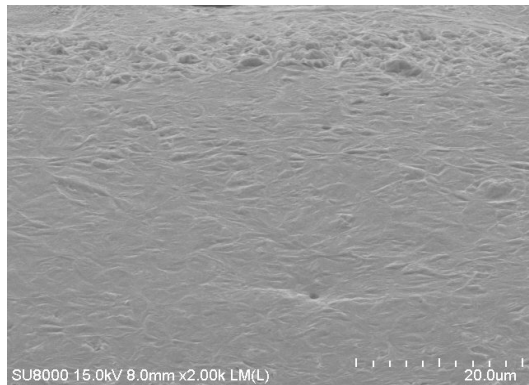


TCT

19.2um max

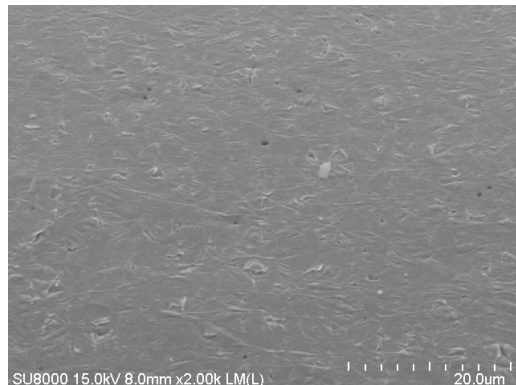


14.7um

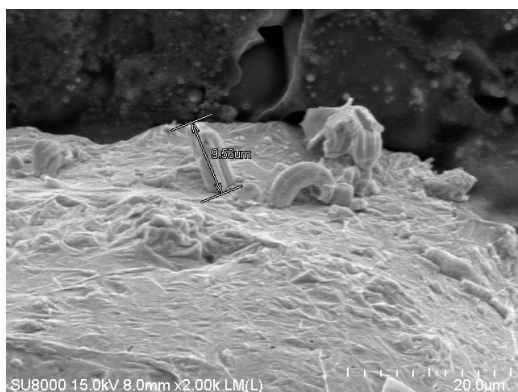


THT

No Whisker

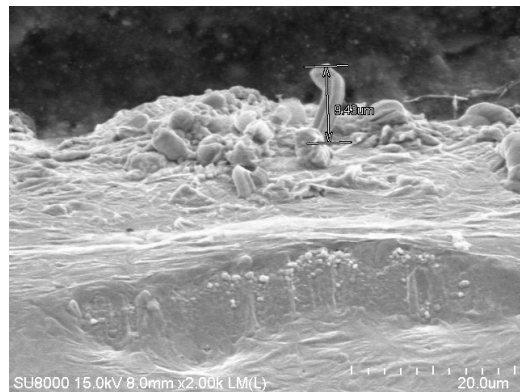


No Whisker



HT&T

9.56um max



9.43um